Nidec Advance Technology Corporation

March 17, 2026

Nidec Advance Technology to Exhibit Products at CPCA Show 2026

Nidec Advance Technology Corporation (“Nidec Advance Technology” or the “Company”) announced today that it will exhibit products at CPCA Show 2026, an event to be held at the National Exhibition and Convention Center (Shanghai) in Shanghai, China, from Tuesday, March 24 – Thursday, March 26, 2026.

This upcoming exhibition to be hosted by the China Printed Circuit Association (CPCA) is an international fair to showcase substrate technologies that require extremely high expertise in the world’s electronic circuit market and are essential to electronic, information, telecommunication, and control equipment and devices.

Visitors to Nidec Advance Technology’s booth will be able to see on display an actual 48K machine, the latest model from the Company’s SREC M1 series, which is highly popular in the Chinese market, and experience through demonstration the product’s overwhelmingly high processing capability and inspection accuracy.

In addition, to address automation and labor saving – two of urgent issues at manufacturing scene – the Company will introduce its automated guided vehicles (AGVs) linked with inspection instrument to offer consistent automatic transfer solutions for substrate manufacturing processes.

Furthermore, for high-layer substrates, which are in increasing demand in recent years, Nidec Advance Technology will exhibit its latest inspection solutions to manage the quality of back drill machining.

About CPCA Show 2026
- Period: Tuesday, March 24 – Thursday, March 26, 2026
- Venue: National Exhibition and Convention Center (Shanghai)
- Nidec Advance Technology’s booth: 7B07
- Official website: http://www.cpcashow.com/en

Nidec Advance Technology’s exhibits will include:
- GATS series (continuity/short circuit inspection instrument for advanced packages)
- SREC series (continuity/short circuit inspection instrument for HDI and PCB)
- GATS-8360 (continuity/short circuit inspection instrument for large HDI)
- RSH-S80iAMPTV (2D/3D Bump optical inspection instrument for IC substrates)
- High -precision 2D/3D inspection solutions for TGV
- X-ray inspection instrument for CT
- AURCA series (3D/AFVI+AI inspection instrument for large substrates)
- AURCA-S series (2D + 3D inspection instrument for wafers and PLP)
- NATS-2120 (instrument to inspect power semiconductor-equipped substrates)

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